



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250319003.1

**Qualification of DFAB as an additional Fab site option for select JIBB devices
Change Notification / Sample Request**

Date: June 04, 2025

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#)

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

Changes outlined in this notification underscore our commitment to product longevity and supply continuity, as well as our continued efforts to transition to newer, more efficient manufacturing processes and technologies. Specifically, this particular notification is related to TI's multiyear transition plan for our two remaining 150-millimeter production lines (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). SFAB closure activities are expected to begin by the end of 2025. DFAB will remain open with a smaller set of 200mm technologies and GaN.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20250319003.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA121UA	
DRV135UA/2K5	
REF102AU/2K5	
INA2137UA	
ISO124P	
INA2134UA	
ISO124U/1K	
INA2134UA/2K5	
OPA548F/500	
OPA551FA/500	
INA111AP	
DRV135UA	
OPA548F/500	
OPA551UA/2K5	
ISO122U	
OPA551UA	
INA2141UA	
INA128HD	
OPA544T	
OPA551FAKTWT	
INA157U/2K5	
REF102BU	
INA138NA/3K	
OPA548FKTWT	
DRV134PA	
INA121PA	
ISO122JP	
OPA2604AU	
REF02BU/2K5	
INA134UA	
REF02AU/2K5	
REF102BU	
INA103KP	
REF02BU/2K5	
OPA548T-1	
INA2141UA/1K	
ISO122JPE4	
ISO124U	
INA111BU	
INA166UA/2K5	
OPA2604AU/2K5	
OPA544T	
DRV134UA/1K	
INA169NA/250	
INA2141U	
INA2141UA	
REF102AU	
REF02AU	
INA2134UA/2K5	
ISO122PE4	
OPA544F/500	

INA103KU/1K	
INA128P	
OPA551UA/2K5	
INA128PA	
INA137UA/2K5	
REF102CU	
ISO122P	
OPA551UA	
INA168NA/3K	
INA134UA/2K5	
INA139NA/250	
INA121UA/2K5	
INA121U	
INA121UA/2K5	
DRV135UA	
DRV134UA	
INA138NA/3K	
INA168NA/250	
ISO124U	
ISO122JU	
REF102CU	
ISO122U/1K	
REF02AU/2K5	
REF02BU	
INA121U	
INA137UA/2K5	
INA157UA/2K5	
OPA551FA/500G3	
INA103KU	
INA139NA/3K	
OPA544FKTTT	
INA128PA	
OPA548T	
INA139NA/3K	
ISO122JUE4	
INA157U	
INA154U/2K5	
INA111AU/1K	
INA168NA/3K	
INA2137UA	
INA111AU	
INA121U/2K5	
INA137UA	
INA121P	
INA154U	
INA2137UA/2K5	
INA111BP	
OPA548T-1	
INA103KU	
INA121U/2K5	
DRV134PA	
OPA548T	
INA168NA/250	
OPA551FA/500	
INA137UA	
INA138NA/250	
INA154UA	
OPA551FAKTWTG3	
ISO122P	
REF102CU/2K5	
INA138NA/250	
ISO122U	

ISO122JP	
REF102AU/2K5	
OPA551FAKTWT	
INA169NA/3K	
ISO124P	
OPA551PA	
OPA548FKTWT	
INA134UA/2K5	
ISO122JU	
INA154U/2K5	
ISO124U/1KE4	
INA139NA/250	
REF02AU	
ISO122JU/1K	
DRV135UA/2K5	
INA169NA/3K	
INA169NA/250	

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250319003.1	PCN Date:	June 04, 2025																		
Title:	Qualification of DFAB as an additional Fab site option for select JIBB devices																				
Customer Contact:	Change Management Team	Dept:	Quality Services																		
Proposed 1st Ship Date:	September 02, 2025	Sample requests accepted until:	August 03, 2025*																		
*Sample requests received after August 03, 2025 will not be supported.																					
Change Type:																					
☐ Assembly Site	☐ Design	☐ Wafer Bump Material																			
☐ Assembly Process	☐ Data Sheet	☐ Wafer Bump Process																			
☐ Assembly Materials	☐ Part number change	☒ Wafer Fab Site																			
☐ Mechanical Specification	☐ Test Site	☒ Wafer Fab Material																			
☐ Packing/Shipping/Labeling	☐ Test Process	☐ Wafer Fab Process																			
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the addition of DFAB as an additional Wafer Fab option for the devices listed below.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>SFAB</td> <td>JIBB</td> <td>150 mm</td> <td>DFAB</td> <td>JIBB</td> <td>200 mm</td> </tr> </tbody> </table>				Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	SFAB	JIBB	150 mm	DFAB	JIBB	200 mm
Current Fab Site			Additional Fab Site																		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																
SFAB	JIBB	150 mm	DFAB	JIBB	200 mm																
Qual details are provided in the Qual Data Section.																					
Reason for Change:																					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																					
None																					
Changes to product identification resulting from this PCN:																					
Fab Site Information:																					
<table border="1"> <thead> <tr> <th>Chip Site</th> <th>Chip Site Origin Code (20L)</th> <th>Chip Site Country Code (21L)</th> <th>Chip Site City</th> </tr> </thead> <tbody> <tr> <td>SH-BIP-1</td> <td>SHE</td> <td>USA</td> <td>Sherman</td> </tr> <tr> <td>DL-LIN</td> <td>DLN</td> <td>USA</td> <td>Dallas</td> </tr> </tbody> </table>				Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	SH-BIP-1	SHE	USA	Sherman	DL-LIN	DLN	USA	Dallas						
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																		
SH-BIP-1	SHE	USA	Sherman																		
DL-LIN	DLN	USA	Dallas																		
Sample product shipping label (not actual product label):																					
Product Affected:																					

DRV134PA	INA134UA	INA2137UA/2K5	OPA544F/500
DRV134PA.A	INA134UA.A	INA2137UA/2K5.A	OPA544F/500.A
DRV134UA	INA134UA/2K5	INA2141U	OPA544FKTTT
DRV134UA.A	INA134UA/2K5.A	INA2141U.A	OPA544FKTTT.A
DRV134UA/1K	INA137UA	INA2141UA	OPA544T
DRV134UA/1K.A	INA137UA.A	INA2141UA.A	OPA544T.A
DRV135UA	INA137UA/2K5	INA2141UA/1K	OPA548F/500
DRV135UA.A	INA137UA/2K5.A	INA2141UA/1K.A	OPA548F/500.A
DRV135UA/2K5	INA138NA/250	ISO122JP	OPA548FKTWT
DRV135UA/2K5.A	INA138NA/250.A	ISO122JP.A	OPA548FKTWT.A
INA103KP	INA138NA/3K	ISO122JP.B	OPA548T
INA103KP.A	INA138NA/3K.A	ISO122JPE4	OPA548T.A
INA103KU	INA139NA/250	ISO122JU	OPA548T-1
INA103KU.A	INA139NA/250.A	ISO122JU.A	OPA548T-1.A
INA103KU/1K	INA139NA/3K	ISO122JU.B	OPA551FA/500
INA103KU/1K.A	INA139NA/3K.A	ISO122JU/1K	OPA551FA/500.A
INA111AP	INA154U	ISO122JU/1K.A	OPA551FA/500G3
INA111AP.A	INA154U.A	ISO122JU/1K.B	OPA551FAKTWT
INA111AU	INA154U/2K5	ISO122JUE4	OPA551FAKTWT.A
INA111AU.A	INA154U/2K5.A	ISO122P	OPA551FAKTWTG3
INA111AU/1K	INA154UA	ISO122P.A	OPA551PA
INA111AU/1K.A	INA154UA.A	ISO122P.B	OPA551PA.A
INA111BP	INA157U	ISO122PE4	OPA551UA
INA111BP.A	INA157U.A	ISO122U	OPA551UA.A
INA111BU	INA157U/2K5	ISO122U.A	OPA551UA/2K5
INA111BU.A	INA157U/2K5.A	ISO122U.B	OPA551UA/2K5.A
INA121P	INA157UA	ISO122U/1K	REF02AU
INA121P.A	INA157UA.A	ISO122U/1K.A	REF02AU.A
INA121PA	INA157UA/2K5	ISO122U/1K.B	REF02AU/2K5
INA121PA.A	INA157UA/2K5.A	ISO122UE4	REF02AU/2K5.A
INA121U	INA168NA/250	ISO124P	REF02BU
INA121U.A	INA168NA/250.A	ISO124P.A	REF02BU.A
INA121U/2K5	INA168NA/3K	ISO124P.B	REF02BU/2K5
INA121U/2K5.A	INA168NA/3K.A	ISO124U	REF02BU/2K5.A
INA121UA	INA169NA/250	ISO124U.A	REF102AU
INA121UA.A	INA169NA/250.A	ISO124U.B	REF102AU.A
INA121UA/2K5	INA169NA/3K	ISO124U/1K	REF102AU/2K5
INA121UA/2K5.A	INA169NA/3K.A	ISO124U/1K.A	REF102AU/2K5.A
INA128HD	INA2134UA	ISO124U/1K.B	REF102BU
INA128HD.A	INA2134UA.A	ISO124U/1KE4	REF102BU.A
INA128P	INA2134UA/2K5	ISO124UE4	REF102CU
INA128P.A	INA2134UA/2K5.A	OPA2604AU	REF102CU.A
INA128PA	INA2134UA/2K5G4	OPA2604AU.A	REF102CU/2K5
INA128PA.A	INA2137UA	OPA2604AU/2K5	REF102CU/2K5.A
INA128PG4	INA2137UA.A	OPA2604AU/2K5.A	

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA168QDBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device INA168QDBVRQ1 is qualified at MSL1 260C
- Qual Device INA168QDBVRQ1 is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2206-002

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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